

IEEE's Nanotechnology Conferences with focus in Nanopackaging - Abstracts Due Now

IEEE-NANO is the flagship IEEE International Conference on **Nanotechnology**, which has been a successful annual conference since 2001. Recent conferences were in Macau (2019), Cork (2018), Pittsburgh (2017), Sendai (2016), Rome (2015), and Toronto (2014). Due to the COVID-19 pandemic, the IEEE-NANO 2020 was held virtually.

The conference scope spans both **nanoscience** and **nanotechnology**, including:

- Nanoscale interconnections
- Flexible and hybrid electronics
- Power management, energy storage and harvesting
- Nanomaterials for RF to THz, metasurfaces, plasmonics
- High-power and High-Reliability packaging
- Bioelectronic packaging
- Package modeling at nanoscale

Conference Dates: July 28th to 30th of 2021.

Abstract Submission: February 28th 2021

Submission of 4-page Manuscript to proceedings: **May 1st 2021**

Abstracts can be submitted at: <https://2021.ieeenano.org/authors/abstract-submission-for-review/>

EPS and NTC welcome you to the 16th IEEE Nanotechnology Materials and Devices Conference (IEEE NMDC 2021), which will be held in Vancouver, BC, Canada from October 17th to 20th, 2021. **NMDC** is a well-received international conference sponsored by the [IEEE Nanotechnology Council](#). It has been held annually rotating in different parts of the world; in 2019 it was in Stockholm, Sweden and is meeting Virtually (due to COVID-19 restrictions) in 2020. IEEE NMDC aims to highlight current work and future directions in nanotechnology-related research in the areas of nanomaterials and fabrication, nanoelectronics, packaging, nanophotonics, bioengineering, devices, and integration.

NMDC 2021 Paper Submission:

Last date for Short Abstract (text only) submission 15-Apr-21

Last date for Regular, Special Session and Invited papers submission
31-May-21

Last date for Final Manuscript submission for Regular, Special Session and Invited papers
10-Aug-21

Abstracts can be submitted at: <https://ieeenmdc.org/nmdc-2021/call-for-papers/author-submissions/>

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